

### **REMARKS**

Claims 1-15 were originally filed in the present Application. Claims 4, 9, 14 and 15 were previously canceled without prejudice or disclaimer. The Applicants presently amend Claims 1 and 10 and do not cancel or add any claims. Accordingly, Claims 1-3, 5-8 and 10-13 are currently pending in the application. Support for the amendments proposed herein may be found in the specification at page 4, lines 2-3 and 19-20.

The references cited by the Examiner in previous Examiner's Actions fail, independently and in combination, to teach or suggest a first conductive trace formed by an internal metallization layer at an outer region of a substrate, wherein the substrate includes interconnects also formed by the internal metallization layer but electrically isolated from the first conductive trace, as recited in Claim 1. The references also fail to teach or suggest a conductive tester runner formed by an internal metallization layer and around a plurality of bond pads formed on a substrate, wherein the substrate includes interconnects also formed by the internal metallization layer but electrically isolated from the conductive tester runner, as recited in Claim 10. More specifically, the cited references merely teach traces formed over a substrate instead of being formed by a metallization layer within the substrate.

For the foregoing reasons, the Applicants respectfully submit that the foregoing claims are allowable. Therefore, a Notice of Allowance for Claims 1-3, 5-8 and 10-13 is respectfully requested.

Should it facilitate allowance of the application, the Examiner is invited to telephone the undersigned attorney.

Respectfully submitted,

HITT GAINES & BOISBRUN, P.C.

A handwritten signature in black ink, appearing to read "Charles W. Gaines", written over a horizontal line.

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